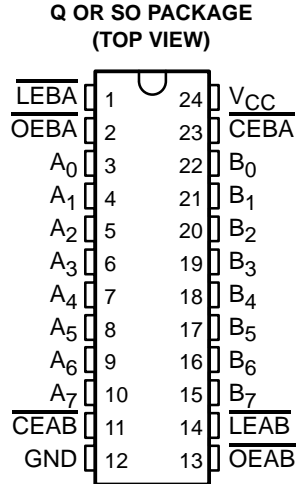


CY74FCT2543T
8-BIT LATCHED TRANSCEIVER
WITH 3-STATE OUTPUTS

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- Function and Pinout Compatible With FCT and F Logic
- 25-Ω Output Series Resistors to Reduce Transmission-Line Reflection Noise
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- 12-mA Output Sink Current
15-mA Output Source Current
- Separation Controls for Data Flow in Each Direction
- Back-to-Back Latches for Storage
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- 3-State Outputs



description

The CY74FCT2543T octal latched transceiver contains two sets of eight D-type latches. Separate latch enable (\overline{LEAB} , \overline{LEBA}) and output enable (\overline{OEAB} , \overline{OEBA}) inputs permit each latch set to have independent control of inputting and outputting in either direction of data flow. For example, for data flow from A to B, the A-to-B enable (\overline{CEAB}) input must be low to enter data from A or to take data from B, as indicated in the function table. With \overline{CEAB} low, a low signal on the A-to-B latch enable (\overline{LEAB}) input makes the A-to-B latches transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode and their outputs no longer change with the A inputs. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B output buffers are active and reflect data present at the output of the A latches. Control of data from B to A is similar, but uses \overline{CEAB} , \overline{LEAB} , and \overline{OEAB} inputs. On-chip termination resistors at the outputs reduce system noise caused by reflections. The CY74FCT2543T can replace the CY74FCT543T to reduce noise in an existing design.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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CY74FCT2543T

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PIN DESCRIPTION

NAME	DESCRIPTION
\overline{OEAB}	A-to-B output-enable input (active low)
\overline{OEBA}	B-to-A output-enable input (active low)
\overline{CEAB}	A-to-B enable input (active low)
\overline{CEBA}	B-to-A enable input (active low)
\overline{LEAB}	A-to-B latch-enable input (active low)
\overline{LEBA}	B-to-A latch-enable input (active low)
A	A-to-B data inputs or B-to-A 3-state outputs
B	B-to-A data inputs or A-to-B 3-state outputs

ORDERING INFORMATION

T _A	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QSOP – Q	Tape and reel	5.3	CY74FCT2543CTQCT	FCT2543C
	SOIC – SO	Tube	5.3	CY74FCT2543CTSOC	FCT2543C
		Tape and reel	5.3	CY74FCT2543CTSOCT	
	QSOP – Q	Tape and reel	6.5	CY74FCT2543ATQCT	FCT2543A
	SOIC – SO	Tube	6.5	CY74FCT2543ATSOC	FCT2543A
		Tape and reel	6.5	CY74FCT2543ATSOCT	
QSOP – Q	Tape and reel	8.5	CY74FCT2543TQCT	FCT2543	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS			LATCH A-TO-B‡	OUTPUT B
\overline{CEAB}	\overline{LEAB}	\overline{OEAB}		
H	X	X	Storing	Z
X	H	X	Storing	X
X	X	H	X	Z
L	L	L	Transparent	Current A inputs
L	H	L	Storing	Previous A inputs

‡ Before \overline{LEAB} low-to-high transition

H = High logic level, L = Low logic level, X = Don't care,

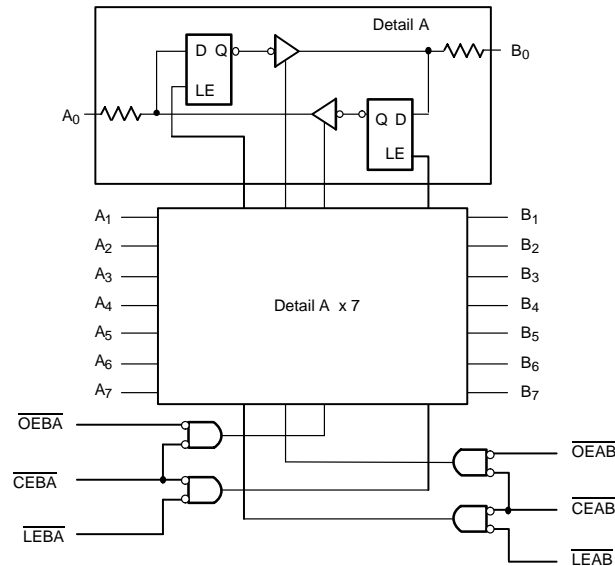
Z = High-impedance state

A-to-B data flow shown; B-to-A is the same, except using \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} .

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functional block diagram



absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	-0.5 V to 7 V
DC input voltage range	-0.5 V to 7 V
DC output voltage range	-0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package	61°C/W
SO package	46°C/W
Ambient temperature range with power applied, T_A	-65°C to 135°C
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			-15	mA
I_{OL}	Low-level output current			12	mA
T_A	Operating free-air temperature	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

CY74FCT2543T

8-BIT LATCHED TRANSCEIVER

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V_{IK}	$V_{CC} = 4.75\text{ V}$,	$I_{IN} = -18\text{ mA}$	-0.7	-1.2		V	
V_{OH}	$V_{CC} = 4.75\text{ V}$,	$I_{OH} = -15\text{ mA}$	2.4	3.3		V	
V_{OL}	$V_{CC} = 4.75\text{ V}$,	$I_{OL} = 12\text{ mA}$		0.3	0.55	V	
R_{out}	$V_{CC} = 4.75\text{ V}$,	$I_{OL} = 12\text{ mA}$	20	25	40	Ω	
V_{hys}	All inputs			0.2		V	
I_{IH}	$V_{CC} = 5.25\text{ V}$	$V_{IN} = V_{CC}$			5	μA	
		$V_{IN} = 2.7\text{ V}$			± 1		
I_{IL}	$V_{CC} = 5.25\text{ V}$,	$V_{IN} = 0.5\text{ V}$			± 1	μA	
I_{OZH}	$V_{CC} = 5.25\text{ V}$,	$V_{OUT} = 2.7\text{ V}$			15	μA	
I_{OZL}	$V_{CC} = 5.25\text{ V}$,	$V_{OUT} = 0.5\text{ V}$			-15	μA	
I_{OS}^{\ddagger}	$V_{CC} = 5.25\text{ V}$,	$V_{OUT} = 0\text{ V}$	-60	-120	-225	mA	
I_{off}	$V_{CC} = 0\text{ V}$,	$V_{OUT} = 4.5\text{ V}$			± 1	μA	
I_{CC}	$V_{CC} = 5.25\text{ V}$,	$V_{IN} \leq 0.2\text{ V}$, $V_{IN} \geq V_{CC} - 0.2\text{ V}$		0.1	0.2	mA	
ΔI_{CC}	$V_{CC} = 5.25\text{ V}$, $V_{IN} = 3.4\text{ V}^{\S}$, $f_1 = 0$, Outputs open			0.5	2	mA	
I_{CCD}^{\uparrow}	$V_{CC} = 5.25\text{ V}$, One input switching at 50% duty cycle, Outputs open, \overline{CEAB} and $\overline{OEAB} = \text{LOW}$, $\overline{CEBA} = \text{HIGH}$, $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$			0.06	1.2	mA/MHz	
$I_C^{\#}$	$V_{CC} = 5.25\text{ V}$, $f_0 = 10\text{ MHz}$, Outputs open, \overline{CEAB} and $\overline{OEAB} = \text{LOW}$, $\overline{CEBA} = \text{HIGH}$, $f_0 = \overline{LEAB} = 10\text{ MHz}$	One bit switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle	$V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$		0.7	1.4	mA
			$V_{IN} = 3.4\text{ V}$ or GND		1.2	3.4	
		Eight bits switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle	$V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$		2.8	5.6	
			$V_{IN} = 3.4\text{ V}$ or GND		5.1	14.6	
C_i				5	10	pF	
C_o				9	12	pF	

† Typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input ($V_{IN} = 3.4\text{ V}$); all other inputs at V_{CC} or GND

↑ This parameter is derived for use in total power-supply calculations.

$I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4\text{ V}$)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_C formula.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER		CY74FCT2543T		CY74FCT2543AT		CY74FCT2543CT		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, \overline{LEBA} or \overline{LEAB} low	5		5		5		ns
t_{su}	Setup time, high or low	A or B before $\overline{LEBA}\downarrow$ or $\overline{LEAB}\downarrow$		2		2		ns
t_h	Hold time, high or low	A or B after $\overline{LEBA}\downarrow$ or $\overline{LEAB}\downarrow$		2		2		ns

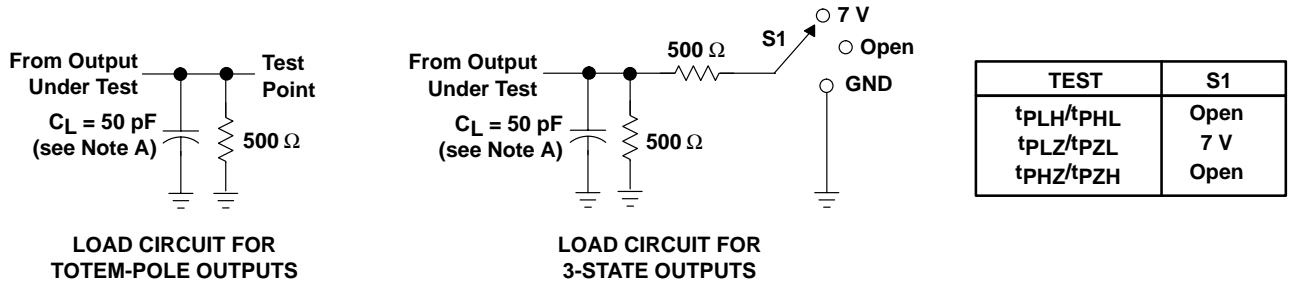
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT2543T		CY74FCT2543AT		CY74FCT2543CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2.5	8.5	2.5	6.5	2.5	5.5	ns
t_{PHL}									
t_{PLH}	\overline{LEBA} or \overline{LEAB}	A or B	2.5	12.5	2.5	8	2.5	7	ns
t_{PHL}									
t_{PZH}	\overline{OEBA} or \overline{OEAB}	A or B	2	12	2	9	2	8	ns
t_{PZL}									
t_{PZH}	\overline{CEBA} or \overline{CEAB}	A or B	2	12	2	9	2	8	ns
t_{PZL}									
t_{PHZ}	\overline{OEBA} or \overline{OEAB}	A or B	2	9	2	7.5	2	6.5	ns
t_{PLZ}									
t_{PHZ}	\overline{CEBA} or \overline{CEAB}	A or B	2	9	2	7.5	2	6.5	ns
t_{PLZ}									

CY74FCT2543T
8-BIT LATCHED TRANSCEIVER
WITH 3-STATE OUTPUTS

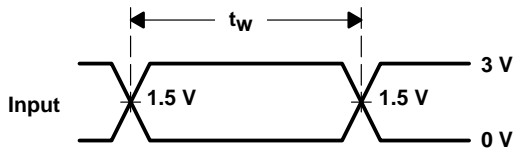
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PARAMETER MEASUREMENT INFORMATION

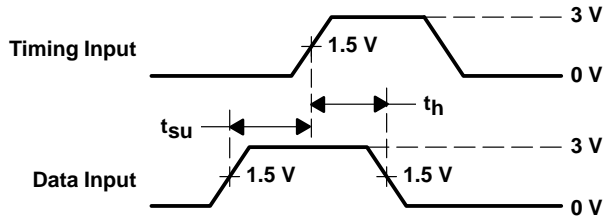


LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

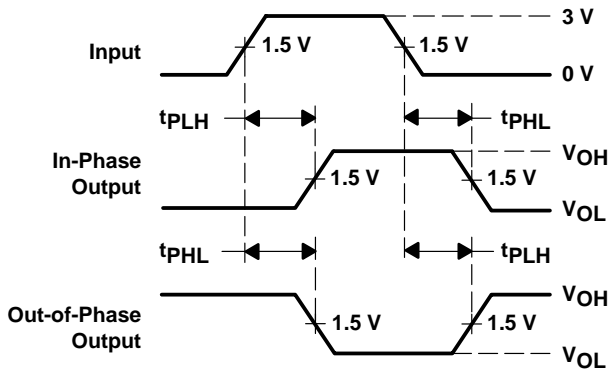
LOAD CIRCUIT FOR 3-STATE OUTPUTS



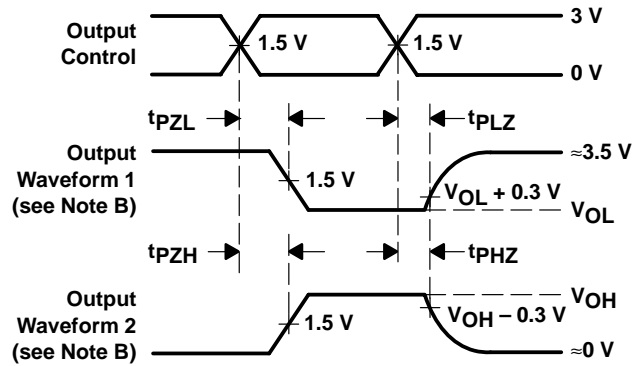
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
74FCT2543ATSOCTE4	ACTIVE	SOIC	DW	24		TBD	Call TI	Call TI	
74FCT2543ATSOCTG4	ACTIVE	SOIC	DW	24		TBD	Call TI	Call TI	
CY74FCT2543ATQCT	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT2543ATQCTE4	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT2543ATQCTG4	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT2543ATSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT2543ATSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT2543ATSOCG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT2543ATSOCT	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	
CY74FCT2543CTQCT	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT2543CTQCTE4	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT2543CTQCTG4	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT2543CTSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT2543CTSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT2543CTSOCG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT2543ATQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2543CTQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT2543ATQCT	SSOP	DBQ	24	2500	367.0	367.0	38.0
CY74FCT2543CTQCT	SSOP	DBQ	24	2500	367.0	367.0	38.0

DW (R-PDSO-G24)

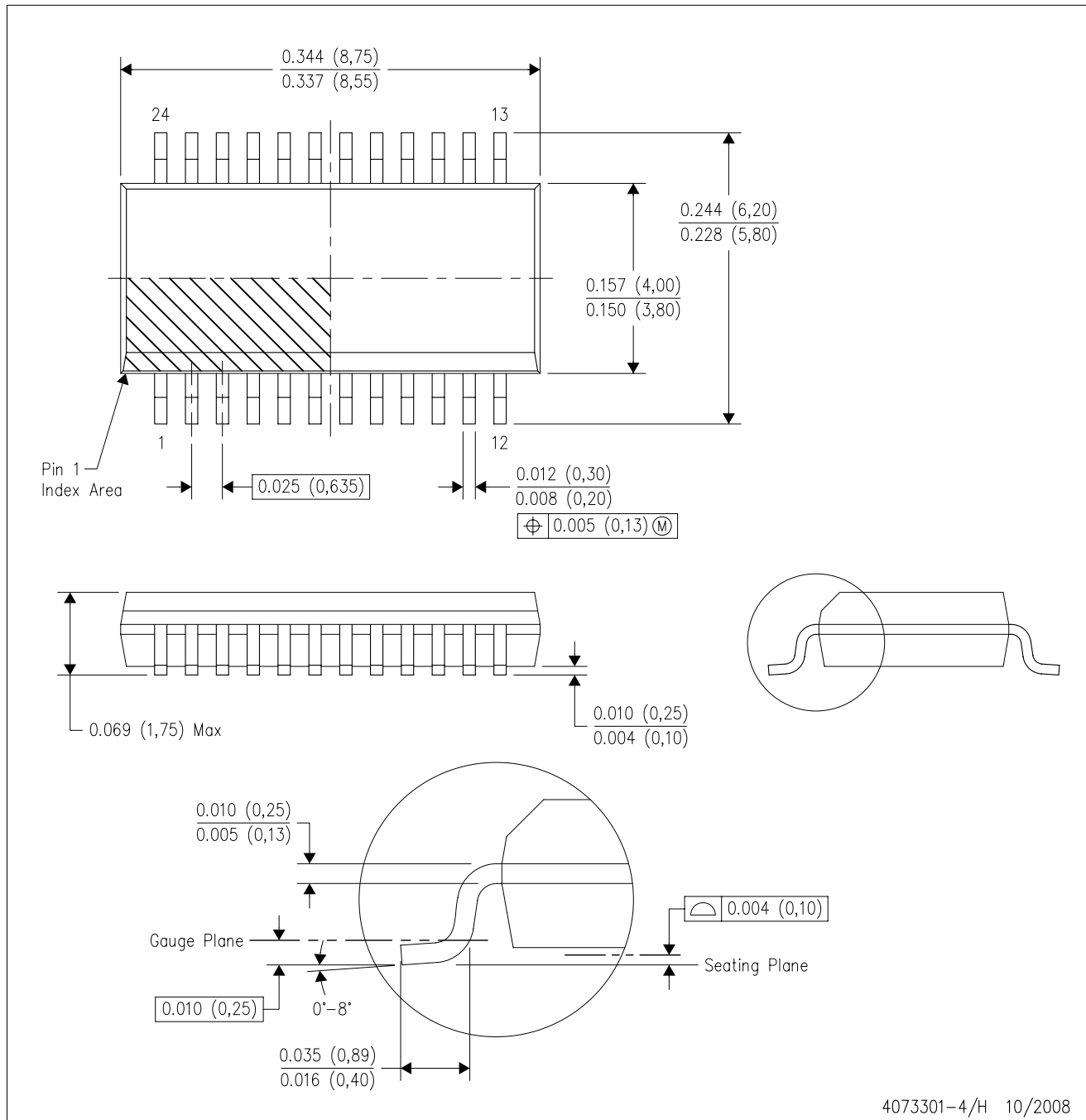
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AD.

DBQ (R-PDSO-G24)

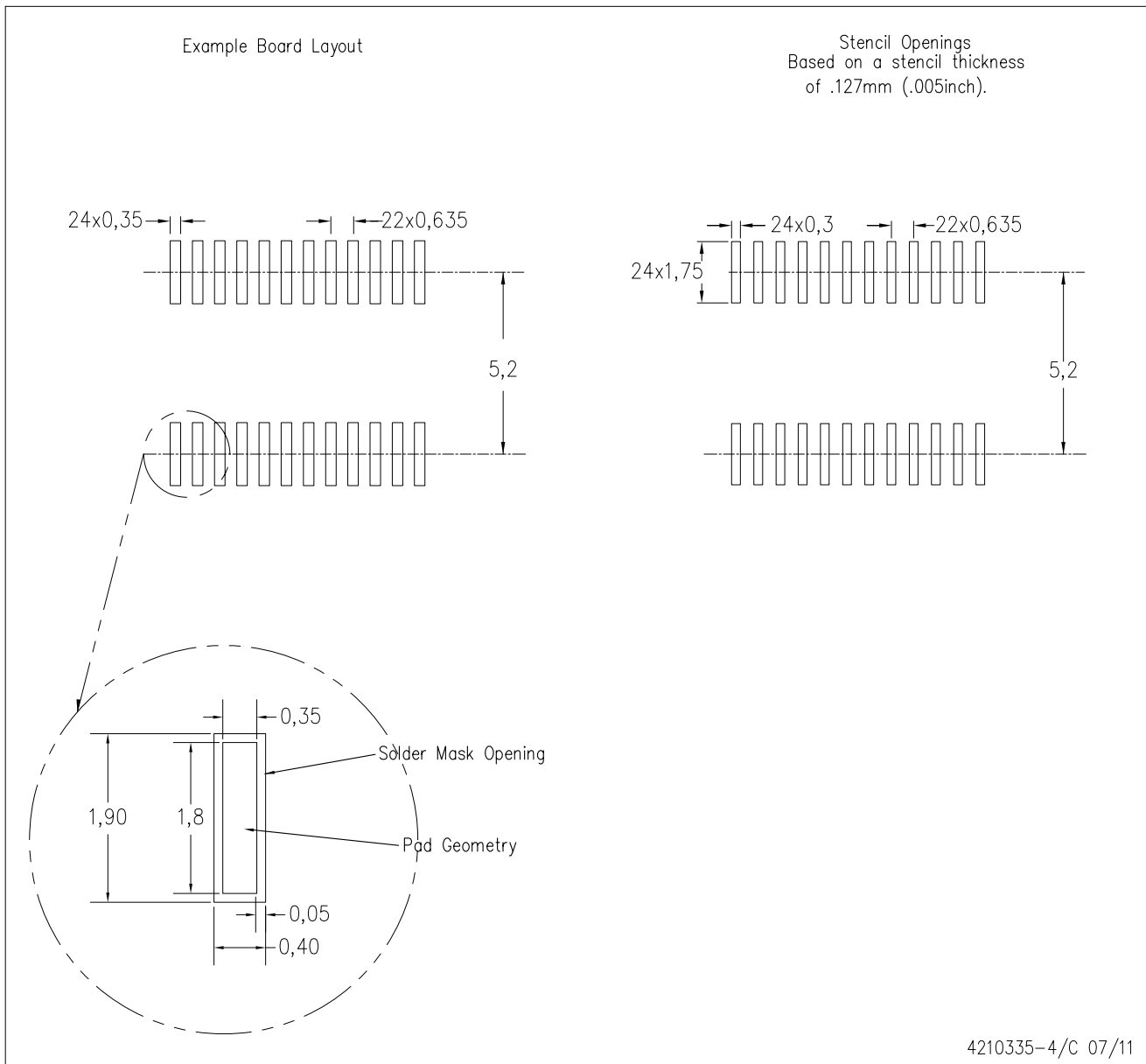
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - Falls within JEDEC MO-137 variation AE.

DBQ (R-PDSO-G24)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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